

Abstract

The invention relates to an electronics housing (1) with a circuit board (4) in the interior (2) of the electronics housing (1), fitted with electronics components (5, 6) on at least one first surface, said first surface facing a first wall (3) of the electronics housing and the interior is filled with a thermally conducting sealing mass (10), at least between the first surface of the circuit board (4) and the first wall (3). According to the invention, local overheating on the external housing surfaces may be avoided whereby a planar heat dissipater (7) is arranged in the sealing mass, between the circuit board and the first wall, which has a higher specific heat conductivity than the sealing mass, whereby inhomogeneous temperature distributions along the surfaces of the first wall are reduced.